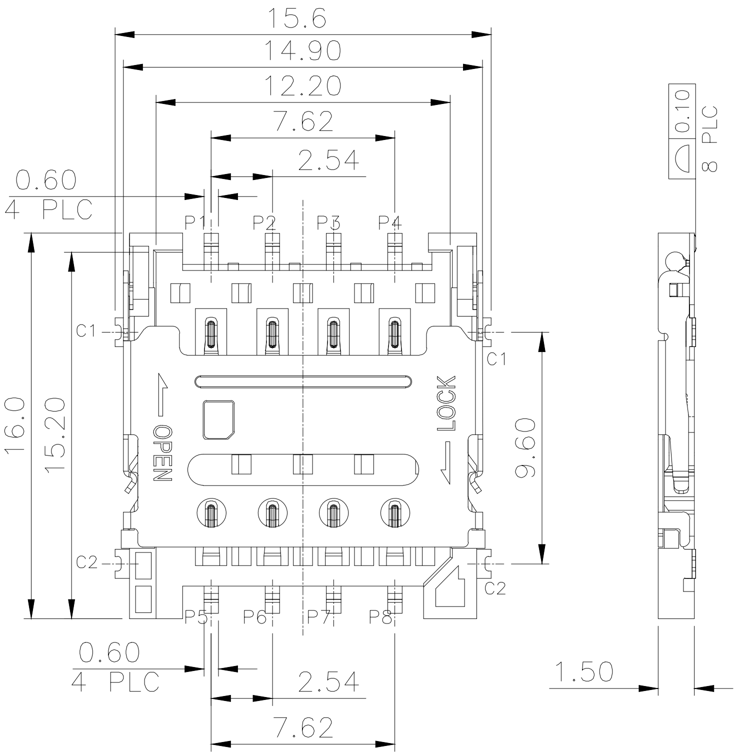
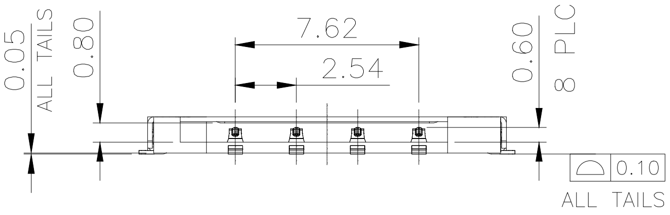
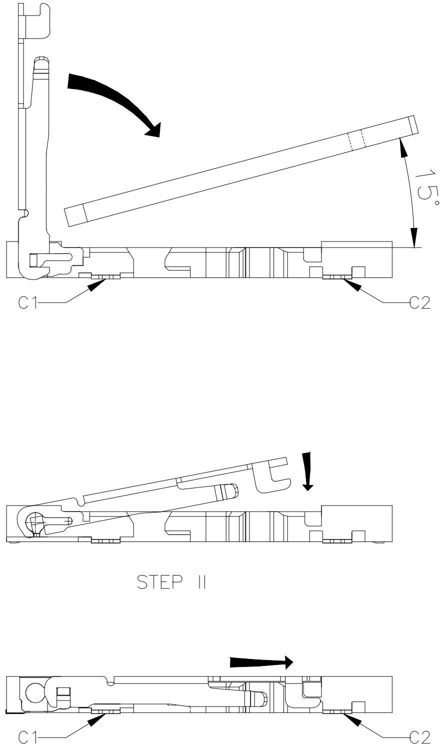
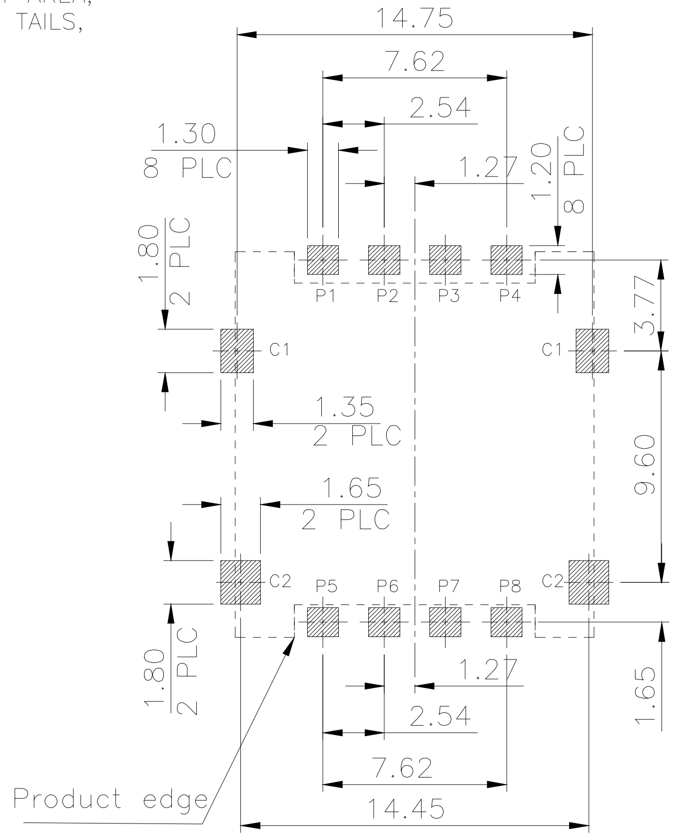
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2015/06/10

NOTES:
1)MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STANLESS STEEL
2)FINISH:
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

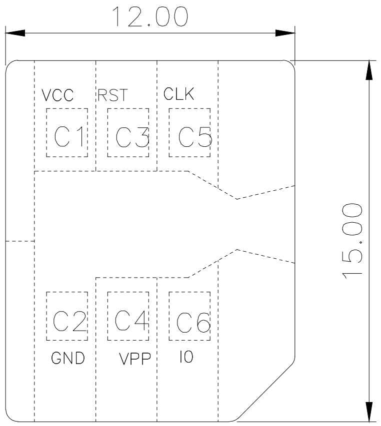








RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05



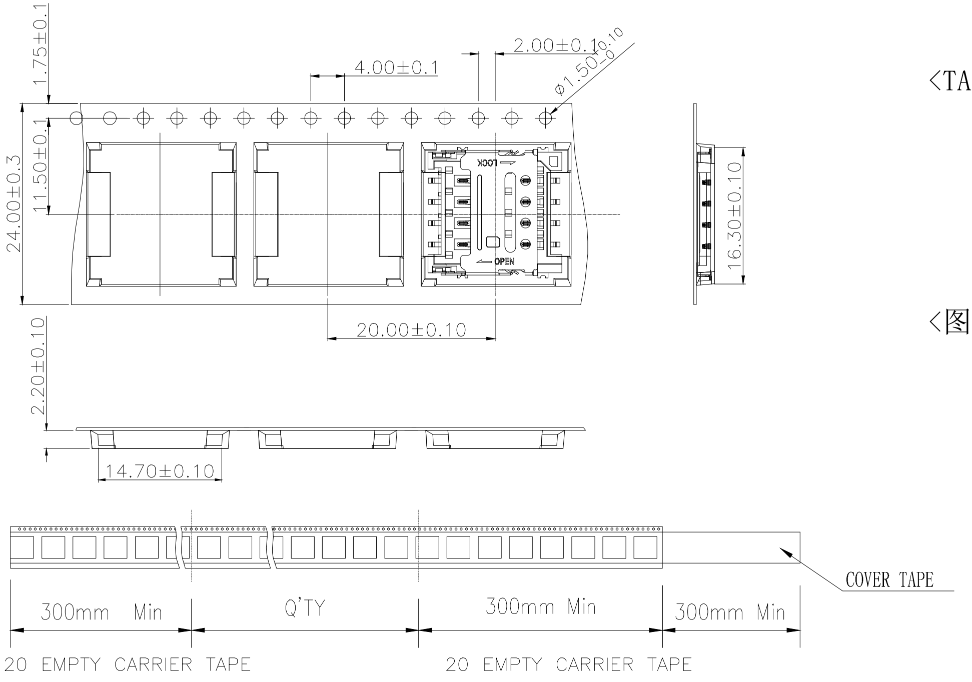
芯片面朝下视图

MICRO SIM CARD	
PIN NO.	DESCRIPTION
P1	VCC
P2	RST
P3	CLK
P4	RESERVED
P5	GND
P6	VPP
P7	I/O
P8	RESERVED

GENERAL TOLERANCE		DWG NO.	JYSA20150610	APPD:		Scale	1:1
X.±0.45	x.°±5°	Title	MICRO SIM CARD 8PIN 1.5H（掀盖式4X2PIN)	CHKD:		UNIT	mm
.X±0.35	.x°±2°			DR:			
.XX±0.25	.xx°±1°	Part NO.	JYS-SIM150-095	Date	2015/06/10		
.XXX±0.15	.xxx°±0.5°		JYSCONN	*Shenzhen JYSCONN Electronics Co., LTD.*			
SHEET	1/2						

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		图面首次发行	2015/06/10

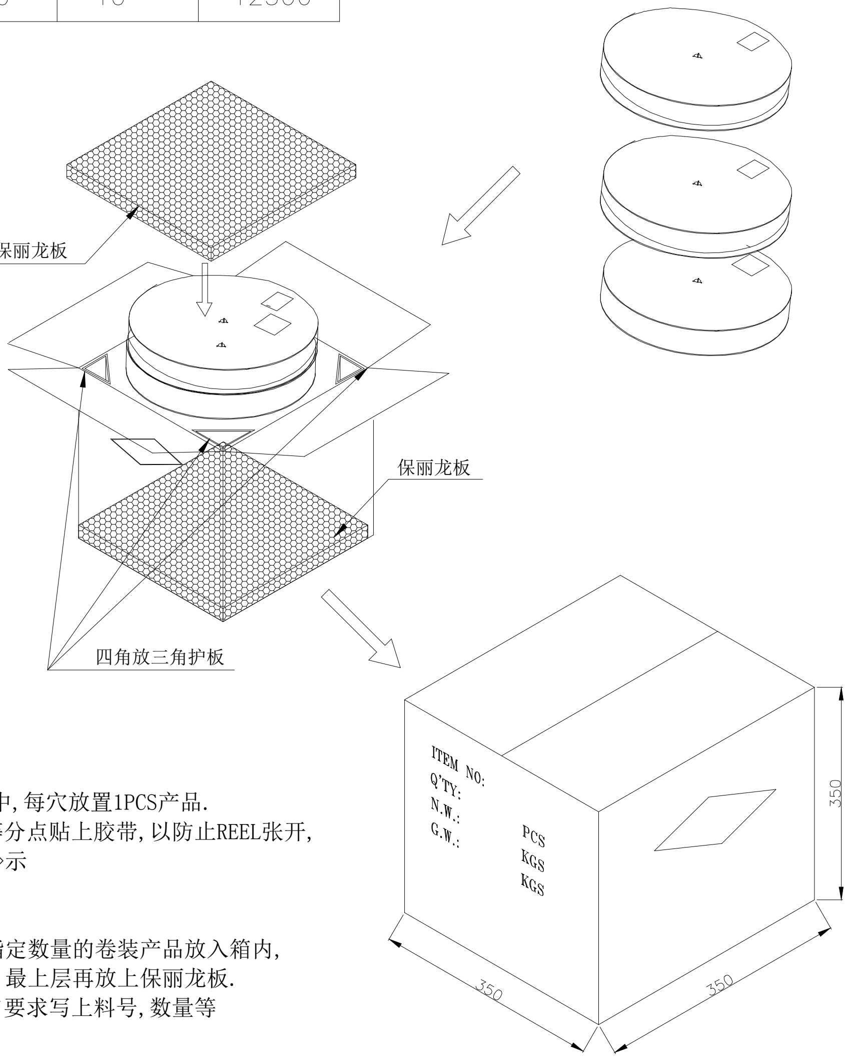
<图一>



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1250	10	12500

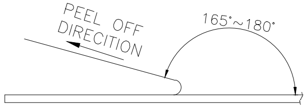
<图三>

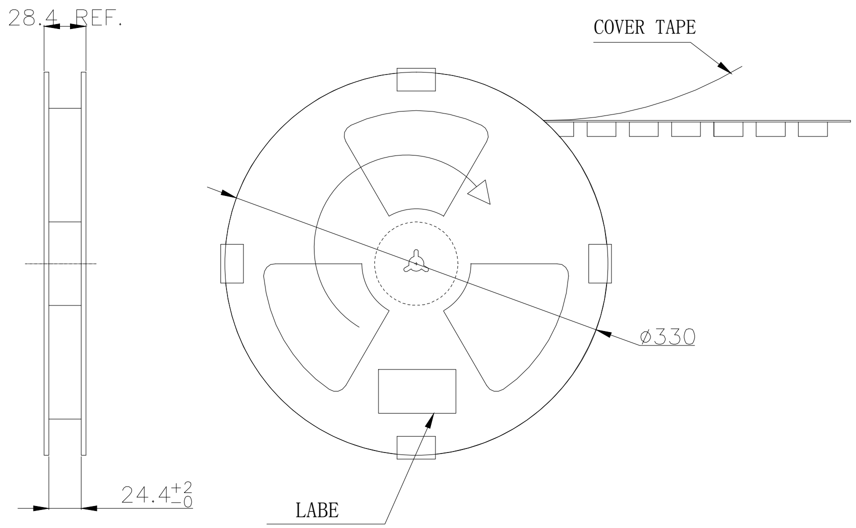


<图二>

放料方向

COVER TAPE PEELING FORCE:50gf~150gf





NOTE:

1.依<图一>示放置产品于下载中,每穴放置1PCS产品.
2.包装机包好后,在REEL的个等分点贴上胶带,以防止REEL张开,
每REEL贴1PCS标签,如<图二>示
3.包装数量见如<TABLE 1>示
4.包装成箱见如<图三>示
箱底放保丽龙板,再依次将指定数量的卷装产品放入箱内,
四角分别放入四个三角护板,最上层再放上保丽龙板.
5.封箱,在封好的纸箱上按客户要求写上料号,数量等

GENERAL TOLERANCE		图 号		设 计		比 例	1:1
X.±0.45	x.°±5°	品 名	MICRO SIM CARD 8PIN 1.5H (4X2 TYPE)包装图	审 核		单 位	mm
.X±0.35	.x°±2°			核 准			
.XX±0.25	.xx°±1°	料 号	JYS-SIM150-095	日 期	2015/06/10		
.XXX±0.15	.xxx°±0.5°		JYSCONN	Shenzhen JYSCONN Electronics Co., LTD.			
页号	2/2						